



**Product Summary**

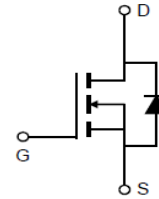
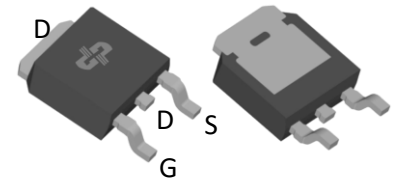
Part #	V <sub>DS</sub>	R <sub>DS(on).typ</sub>	I <sub>D</sub>
DP3080C	30V	3.6mΩ	80A

**Features**

- Advanced high cell desity Trench MOSFET technology
- Better R<sub>DS(on)</sub> enabled by a low R<sub>DSon.sp</sub>, low conduction losses
- Excellent Q<sub>g</sub>xR<sub>DS(on)</sub> product(FOM)
- Qualified according to JEDEC criteria

**Applications**

- Battery management
- Power Management Switches



100% Avalanche Tested

100% Rg Tested

**Package Marking and Ordering Information**

Part #	Marking	Package	Packing
DP3080C	DP3080C	TO-252	Tube/Reel



**Absolute Maximum Ratings**

Parameter	Symbol	Value	Unit
Drain-source voltage	V <sub>DS</sub>	30	V
Continuous drain current T <sub>C</sub> = 25°C (Silicon limit) T <sub>C</sub> = 25°C (Package limit) T <sub>C</sub> = 100°C (Silicon limit)	I <sub>D</sub>	101 80 64	A
Pulsed drain current (T <sub>C</sub> = 25°C, t <sub>p</sub> limited by T <sub>jmax</sub> )	I <sub>D pulse</sub>	320	A
Avalanche energy, single pulse (l=0.3mH, Rg=25) <sup>[1]</sup>	E <sub>AS</sub>	94	mJ
Gate-Source voltage	V <sub>GS</sub>	±20	V
Power dissipation (T <sub>C</sub> = 25°C)	P <sub>tot</sub>	75	W
Operating junction and storage temperature	T <sub>j</sub> , T <sub>stg</sub>	-55...+150	°C

[1].EAS is tested at starting T<sub>j</sub> = 25°C, V<sub>GS</sub> = 10V.

**Thermal Resistance**

Parameter	Symbol	Max	Unit
Thermal resistance, junction – case.	R <sub>thJC</sub>	1.67	°C/W
Thermal resistance, junction – ambient(min. footprint)	R <sub>thJA</sub>	62	

**Electrical Characteristic (at T<sub>j</sub> = 25 °C, unless otherwise specified)**

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		

**Static Characteristic**

Drain-source breakdown voltage	BV <sub>DSS</sub>	30	-	-	V	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA
Gate threshold voltage	V <sub>GS(th)</sub>	0.8	1.3	1.8	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA
Zero gate voltage drain current	I <sub>DSS</sub>	-	-	1	μA	V <sub>DS</sub> =30V, V <sub>GS</sub> =0V T <sub>j</sub> =25°C T <sub>j</sub> =150°C
Gate-source leakage current	I <sub>GSS</sub>	-	-	±100	nA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V
Drain-source on-state resistance	R <sub>DS(on)</sub>	-	3.6	4.3	mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> =40A
		-	4.9	6.1	mΩ	V <sub>GS</sub> =4.5V, I <sub>D</sub> =25A
Gate resistance	R <sub>g</sub>	-	2.5	3.7	Ω	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz
Transconductance <sup>[2]</sup>	g <sub>fs</sub>	-	110	-	S	V <sub>DS</sub> =5V, I <sub>D</sub> =40A

**Dynamic Characteristic<sup>[2]</sup>**

Input Capacitance	C <sub>iss</sub>	-	2216	-	pF	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz
Output Capacitance	C <sub>oss</sub>	-	289	-		
Reverse Transfer Capacitance	C <sub>rss</sub>	-	225	-		
Gate Total Charge(V <sub>GS</sub> =10V)	Q <sub>g</sub>	-	48	-	nC	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =40A, f=1MHz
Gate Total Charge(V <sub>GS</sub> =4.5V)	Q <sub>g</sub>	-	23.5	-		
Gate-Source charge	Q <sub>gs</sub>	-	8.7	-		
Gate-Drain charge	Q <sub>gd</sub>	-	10.5	-		
Turn-on delay time	t <sub>d(on)</sub>	-	13.8	-	ns	V <sub>GS</sub> =10V, V <sub>DD</sub> =15V, R <sub>G_ext</sub> =2.7Ω
Rise time	t <sub>r</sub>	-	88	-		
Turn-off delay time	t <sub>d(off)</sub>	-	42	-		
Fall time	t <sub>f</sub>	-	94	-		

**Body Diode Characteristic**

Parameter	Symbol	Value			Unit	Test Condition
		min.	typ.	max.		
Body Diode Forward Voltage	$V_{SD}$	-	0.7	1	V	$V_{GS}=0V, I_{SD}=1A$
Diode continuous forward current	$I_S$	-	80	-	A	TC = 25°C
Diode pluse current	$I_{S\ pluse}$	-	320	-	A	TC = 25°C
Body Diode Reverse Recovery Time <sup>[2]</sup>	$t_{rr}$	-	13	-	ns	$I_F=20A, dI/dt=100A/\mu$ s
Body Diode Reverse Recovery Charge <sup>[2]</sup>	$Q_{rr}$	-	4	-	nC	

[2]. Defined by design. Not subject to production test



### Typical Performance Characteristics

Fig 1: Output Characteristics

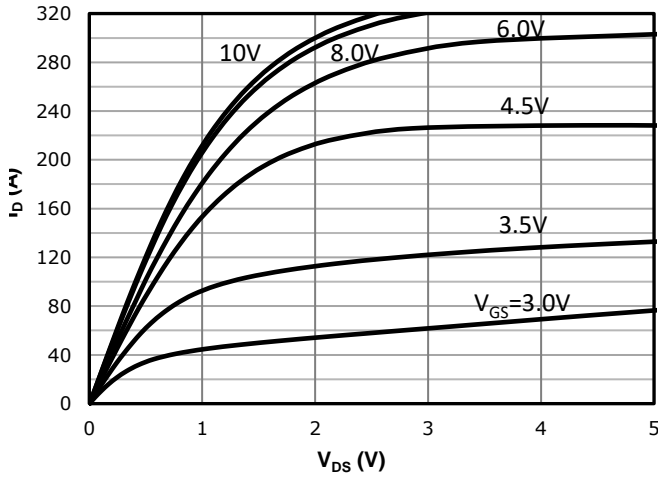


Fig 2: Transfer Characteristics

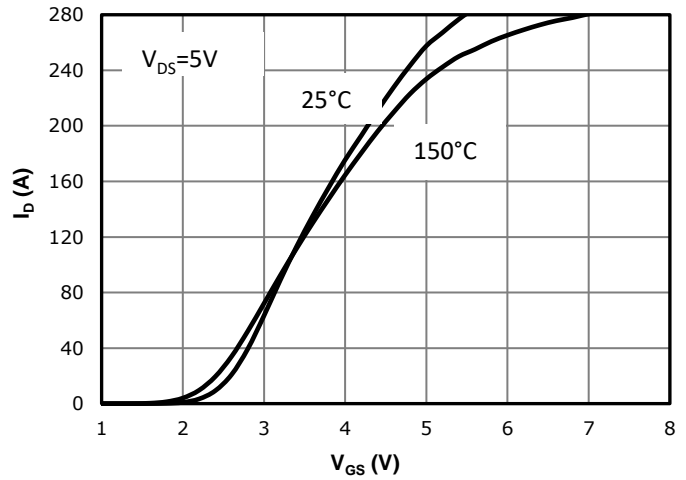


Fig 3: Rds(on) vs Drain Current and Gate Voltage

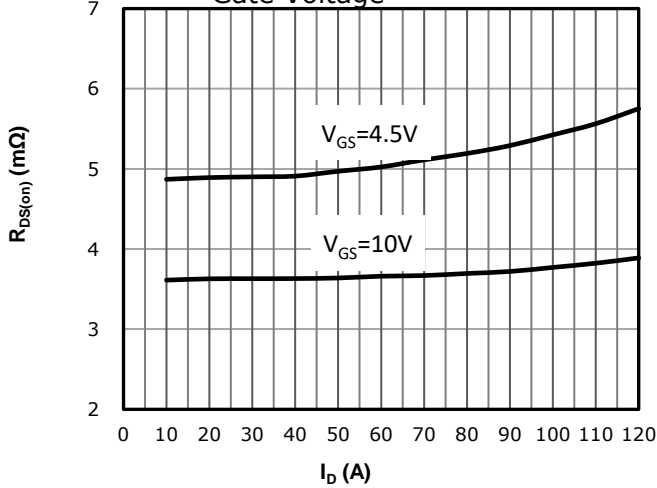


Fig 4: Rds(on) vs Gate Voltage

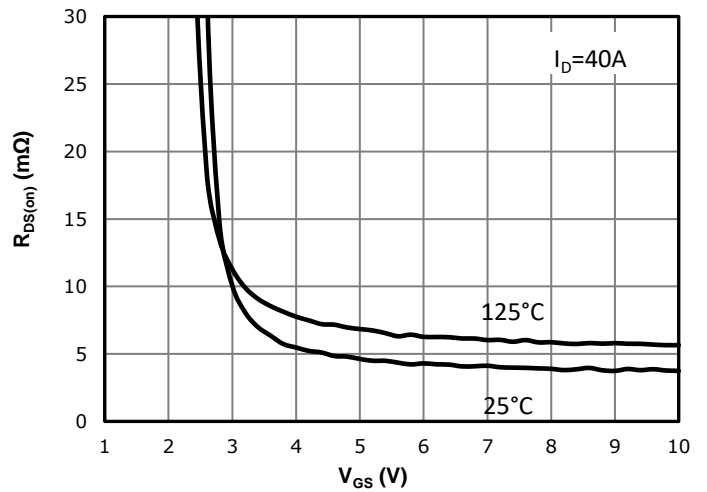


Fig 5: Rds(on) vs. Temperature

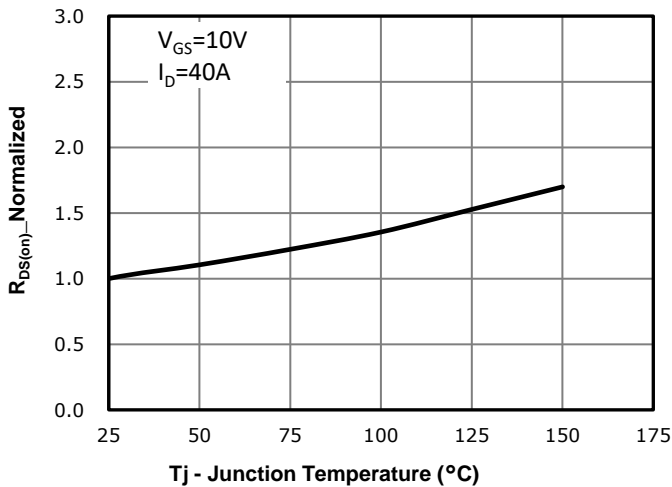


Fig 6: Capacitance Characteristics

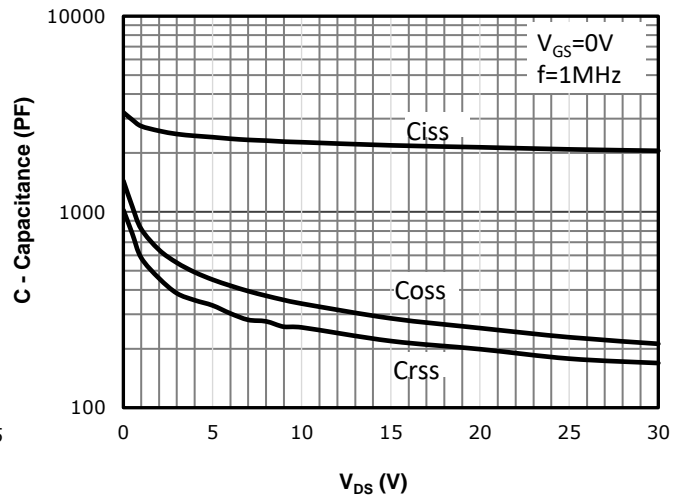




Fig 7: Gate Charge Characteristics

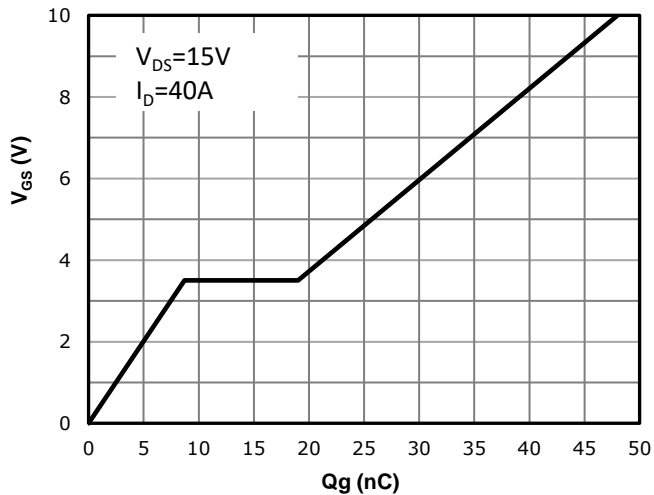


Fig 8: Body-diode Forward Characteristics

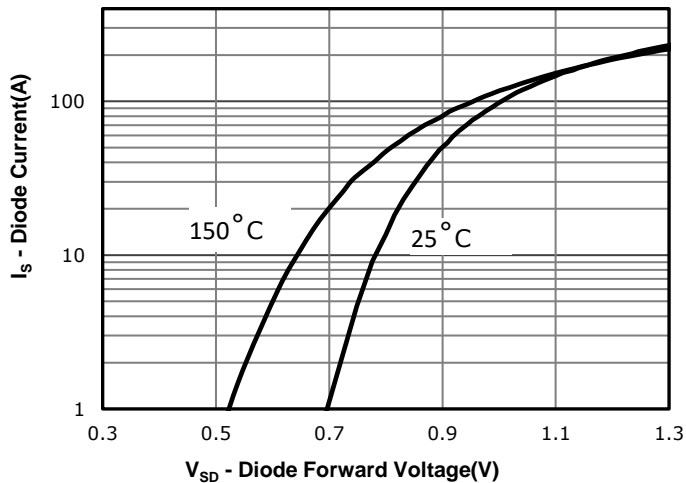


Fig 9: Power Dissipation

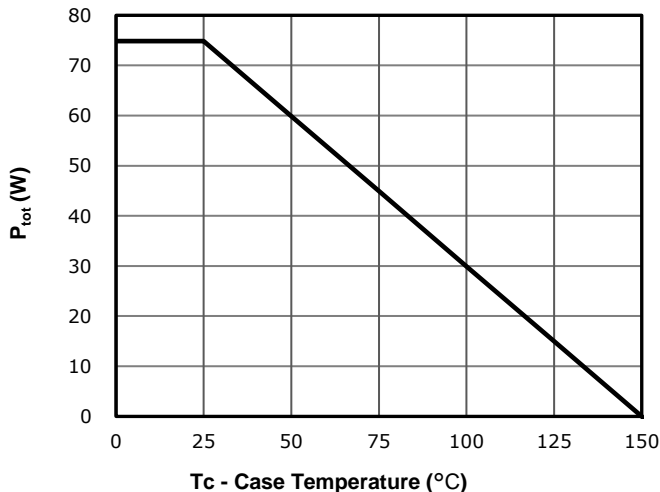


Fig 10: Drain Current Derating

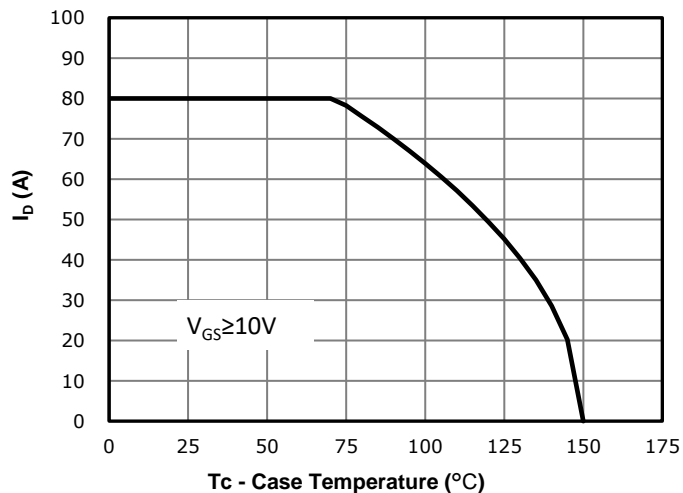


Fig 11: Safe Operating Area

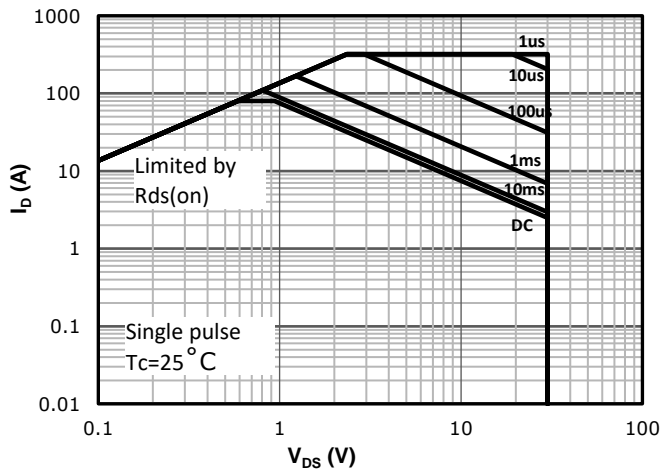
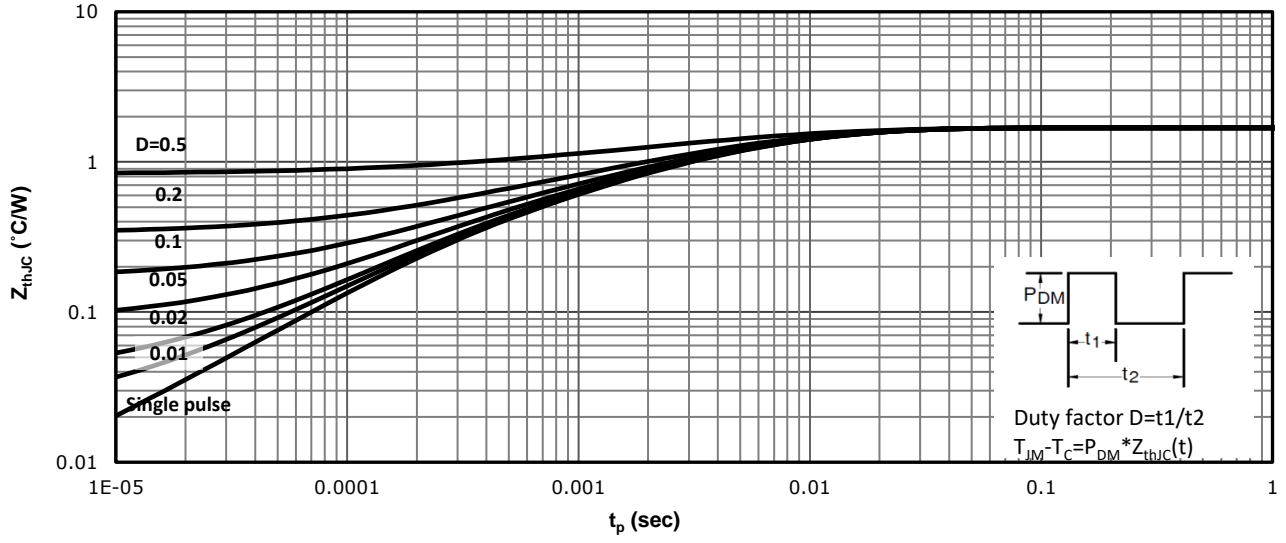




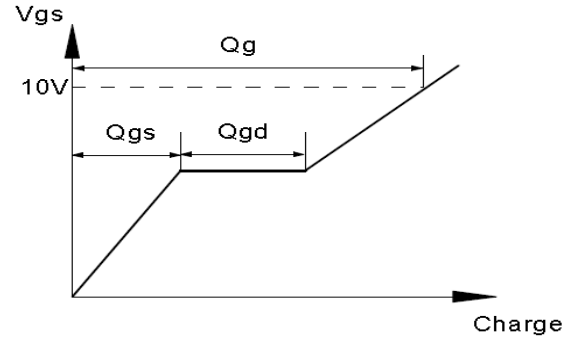
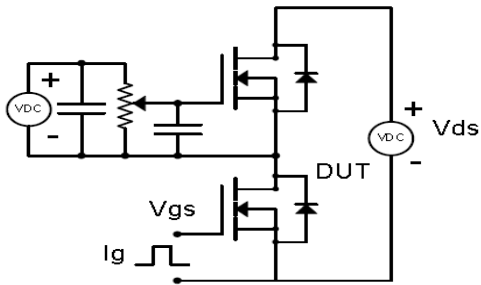
Fig 12: Max. Transient Thermal Impedance



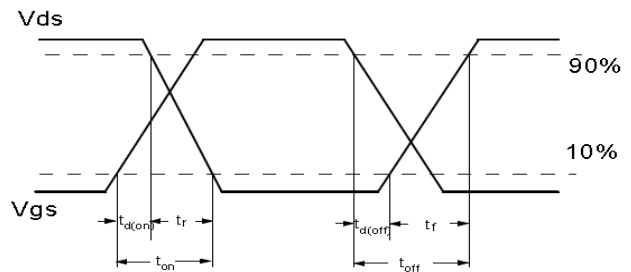
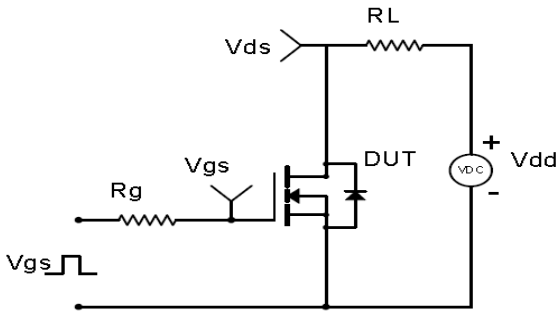


### Test Circuit & Waveform

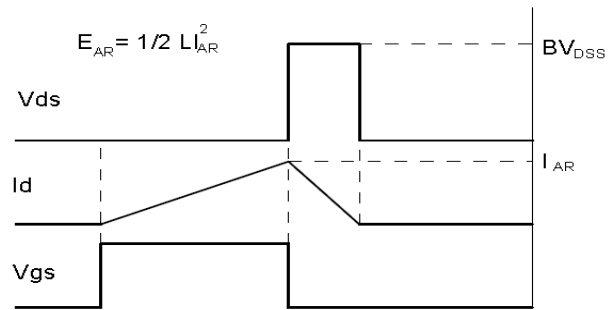
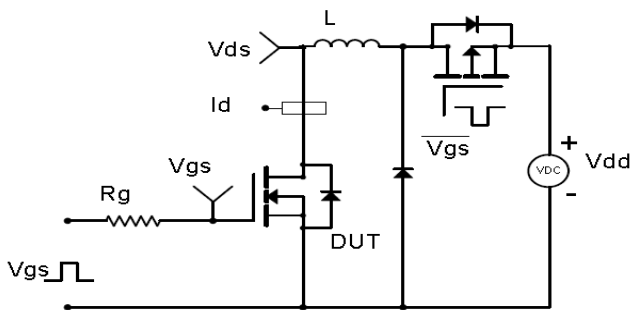
Gate Charge Test Circuit & Waveform



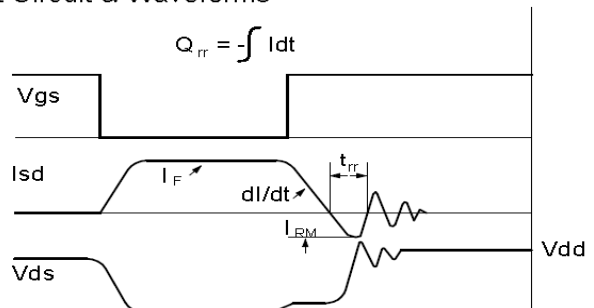
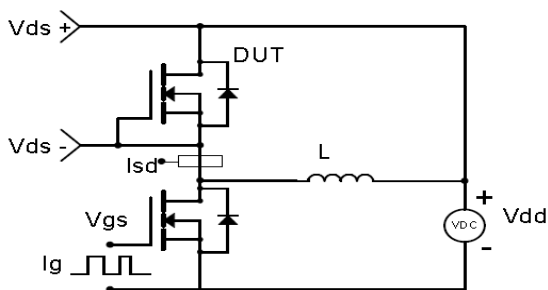
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

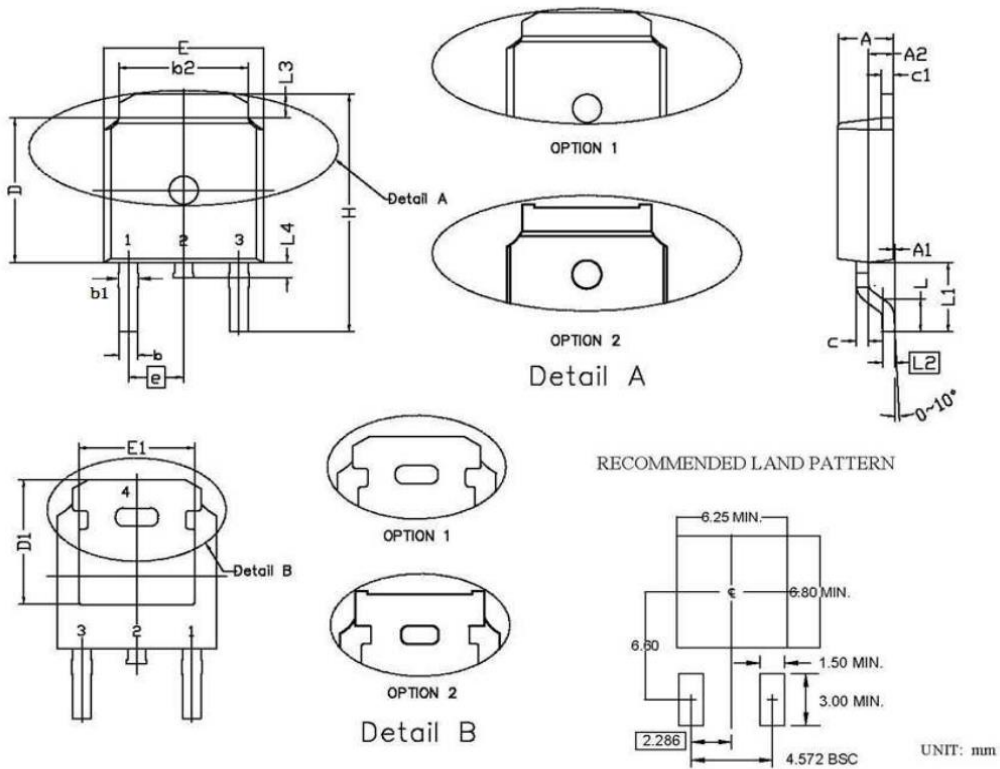


Diode Recovery Test Circuit & Waveforms





**Package Outline: TO-252**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.15	2.45	0.085	0.096
A1	0.00	0.15	0.000	0.006
A2	0.76	1.36	0.030	0.054
b	0.60	0.91	0.024	0.036
b1	0.65	1.15	0.026	0.045
b2	5.00	5.64	0.197	0.222
c	0.45	0.61	0.018	0.024
c1	0.36	0.66	0.014	0.026
D	5.80	6.30	0.228	0.248
D1	5.00	6.00	0.197	0.236
e	2.29 BSC.		0.090 BSC.	
E	6.30	6.90	0.248	0.272
E1	4.55	5.30	0.179	0.209
H	9.40	10.48	0.370	0.413
L	1.18	1.70	0.046	0.067
L1	2.92 REF		0.115 REF	
L2	0.36	0.66	0.014	0.026
L3	0.72	1.35	0.028	0.053
L4	0.60	1.20	0.024	0.047





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## Revision History

Revision	Major changes
1.0	Release for formal version

